

ABSTRACT

An inspection device 1 includes a reference signal output section 24, a noise removal section 25, and an electrical characteristic measurement section 27. The reference signal output section 24 is connected to an external power supply device 2 in electrical parallel with a semiconductor sample S, and outputs a reference signal according to the output of the external power supply device 2. The noise removal section 25 outputs a noise removal signal obtained by removing a noise component of the output of the external power supply device 2 from the current signal output from the semiconductor sample S based on the reference signal. The electrical characteristic measurement section 27 measures the electrical characteristic of the semiconductor sample S based on the noise removal signal. The inspection device 1 measures the electrical characteristic of the semiconductor sample S to which a voltage is being applied by the external power supply device 2 and which is being irradiated and scanned with light. The inspection device 1 outputs a defective portion of the semiconductor sample S based on the electrical characteristic.

Figure 1